

### 描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20V~200V，正向电流：3.0A，SMA封装。

Surface Mount Schottky Barrier Rectifiers, Reverse Voltage : 20 to 200V, Forward Current: 3.0A, SMA package.

### 特征 / Features

低功耗，高效率，高正向浪涌电流能力，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。

Low power loss, high efficiency, High forward surge current capability, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

### 用途 / Applications

一般用途。

General purpose.

### 内部等效电路 / Equivalent Circuit

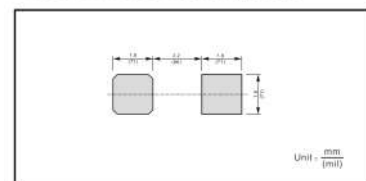


### 引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



### 印章代码 / Marking

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating									单位 Unit
		SS32	SS34	SS345	SS36	SS38	SS310	SS312	SS315	SS320	
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	20	40	45	60	80	100	120	150	200	V
Maximum RMS voltage	V <sub>RMS</sub>	14	28	31.5	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	20	40	45	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3.0									A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	80									A
Typical Junction Capacitance	C <sub>j</sub>	250			180						pF
Typical Thermal Resistance 1)	R <sub>θJA</sub>	70									°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55~+150									°C

Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5 cm) copper pad areas.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating								单位 Unit
			SS32	SS34	SS345	SS36	SS38	SS310	SS312	SS315	
Maximum Instantaneous Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =3.0A	0.55			0.70	0.85			0.95	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I <sub>R</sub>	T <sub>a</sub> =25°C	0.5			0.3					mA
		T <sub>a</sub> =100°C	5.0			3.0					mA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

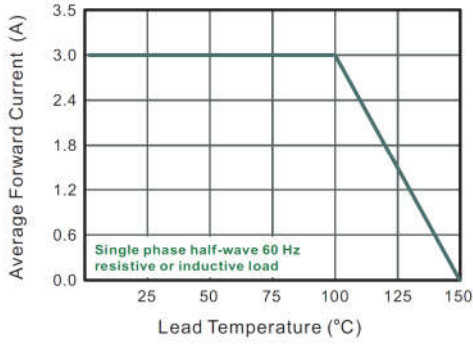


Fig.2 Typical Reverse Characteristics

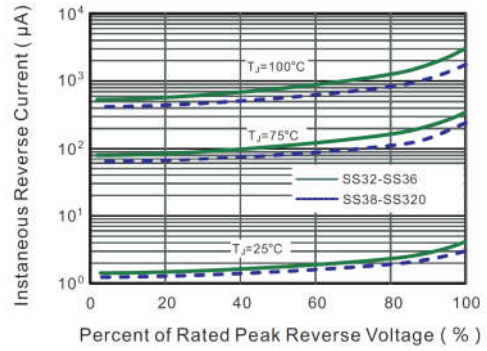


Fig.3 Typical Forward Characteristic

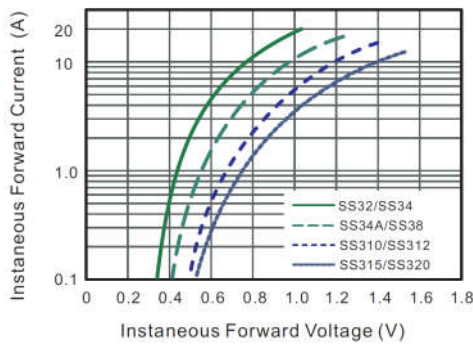


Fig.4 Typical Junction Capacitance

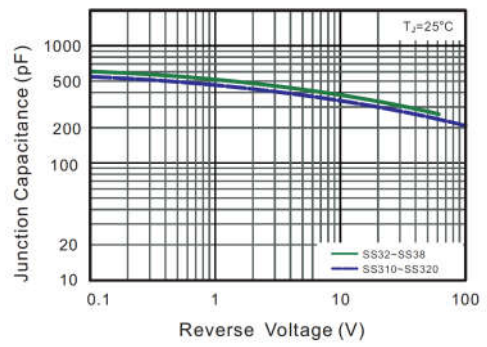


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

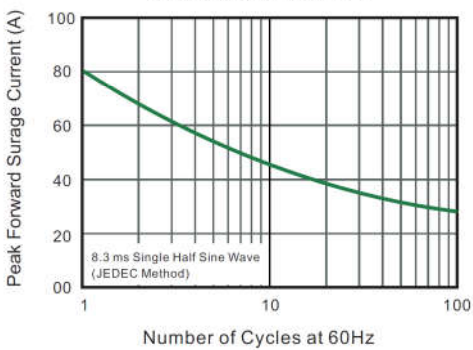
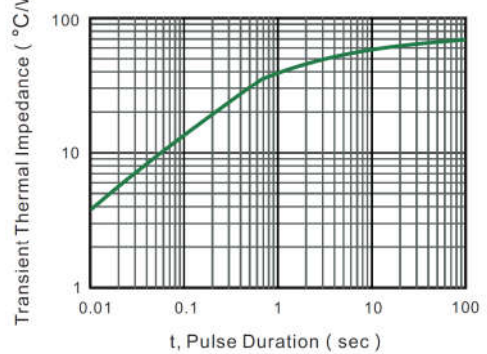
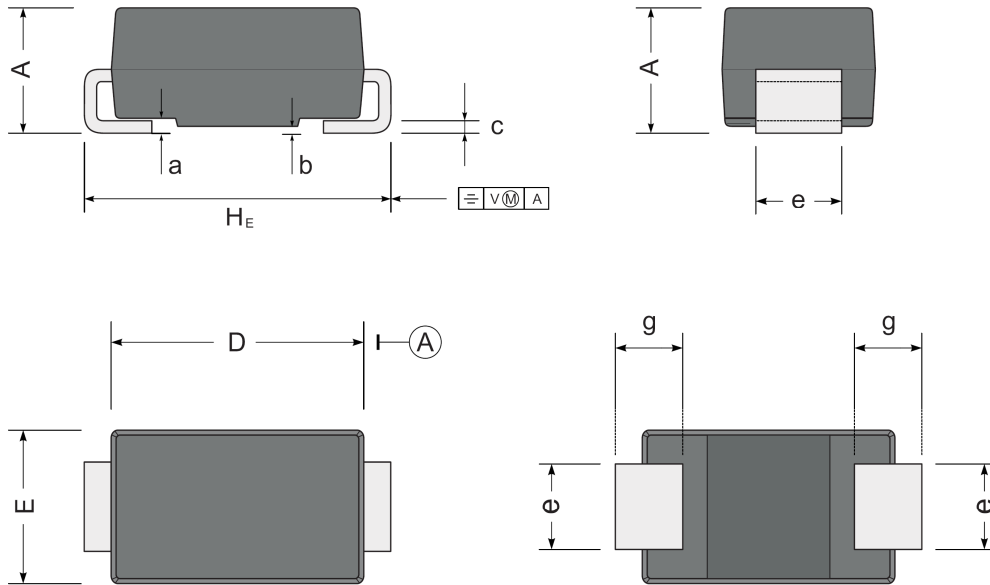


Fig.5- Typical Transient Thermal Impedance



外形尺寸图 / Package Dimensions

SMA



UNIT		A	D	E	H <sub>E</sub>	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

## Marking

Type number	Marking code
SS32	SS32
SS34	SS34
SS34A	SS34A
SS36	SS36
SS38	SS38
SS310	SS310
SS312	SS312
SS315	SS315
SS320	SS320

印章说明 / Marking Instructions



说明：

SS32： 为型号代码

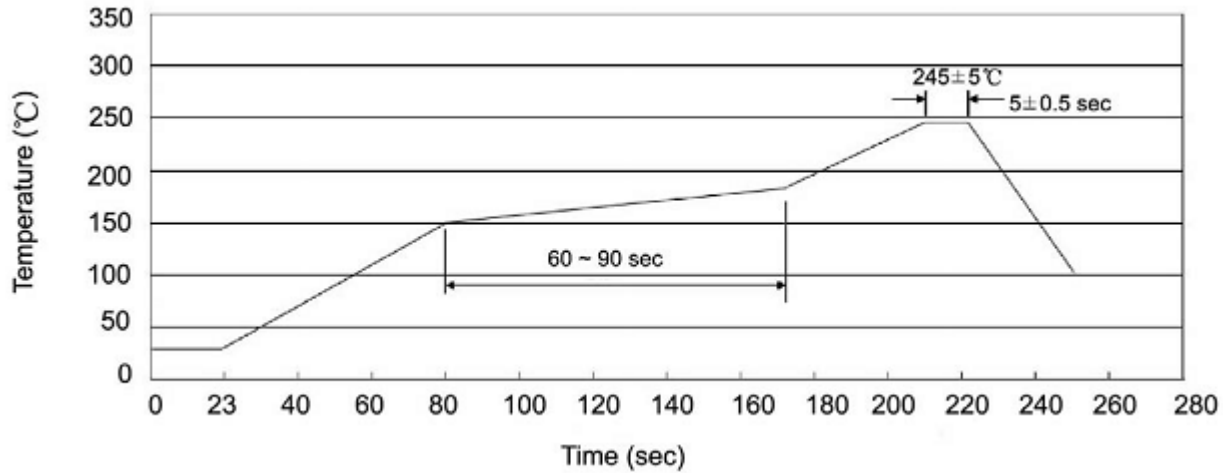
\*\*\*\*： 为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

Note:

SS32： Product Type Code

\*\*\*\*： Lot No. Code ,The 1st \* means:YM Code ,The last 3 \* means:little Lot No  
Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

**使用说明 / Notices**